

Manual Update Sheet

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This Manual Update Sheet appends TMS320C25FNA specifications to the TMS320C25/TMS320E25 Digital Signal Processors Data Sheet (Appendix A) in the *TMS320C2x User's Guide*.

In Appendix A, on page A–19, under **recommended operating conditions**, the TMS320C25GBA and the TMS320C25FNA specs have been included for the V_{IH} $\overline{\text{SYNC}}$ pin and T_A .

recommended operating conditions

			MIN	NOM	MAX	UNIT
V_{IH}	High-level input voltage	CLKIN/CLKX/CLKR (also includes $\overline{\text{SYNC}}$ pin for TMS320C25GBA and TMS320C25FNA)	3.5		$V_{CC}+0.3$	V
T_A	Operating free-air temperature	TMS320C25GBA and TMS320C25FNA	–40		85	°C

On page A–26, under **recommended operating conditions**, the TMS320C25FNA-50 specs for V_{IH} $\overline{\text{INT0}}$ – $\overline{\text{INT2}}$ and $\overline{\text{SYNC}}$ pin inputs, and also T_A are added.

recommended operating conditions

			MIN	NOM	MAX	UNIT
V_{IH}	High-level input voltage	$\overline{\text{INT0}}$ – $\overline{\text{INT2}}$	2.5			V
		$\overline{\text{INT0}}$ – $\overline{\text{INT2}}$ (TMS320C25FNA-50 only)	3.0			V
		CLKIN/CLKX/CLKR (also includes $\overline{\text{SYNC}}$ pin for TMS320C25FNA-50)	3.5			V
T_A	Operating free-air temperature	TMS320C25FNL-50	0		70	°C
		TMS320C25FNA-50	–40		85	°C

On page A–29, under **MEMORY AND PERIPHERAL INTERFACE TIMING, switching characteristics over recommended operating conditions**, the TMS320C25FNA-50 specs for $t_{h(A)}$ and $t_d(\text{MSC})$ have been added.

MEMORY AND PERIPHERAL INTERFACE TIMING

switching characteristics over recommended operating conditions

	PARAMETER	MIN	TYP	MAX	UNIT
$t_{h(A)}$	Address hold time after $\overline{\text{STRB}}$ high (see Note 3)	Q–4			ns
	Address hold time after $\overline{\text{STRB}}$ high for TMS320C25FNA-50 only (see Note 3)	Q–7			ns
$t_d(\text{MSC})$	MSC valid from CLKOUT1	–2			ns
	MSC valid from CLKOUT1 (TMS320C25FNA-50 only)	–5			ns

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